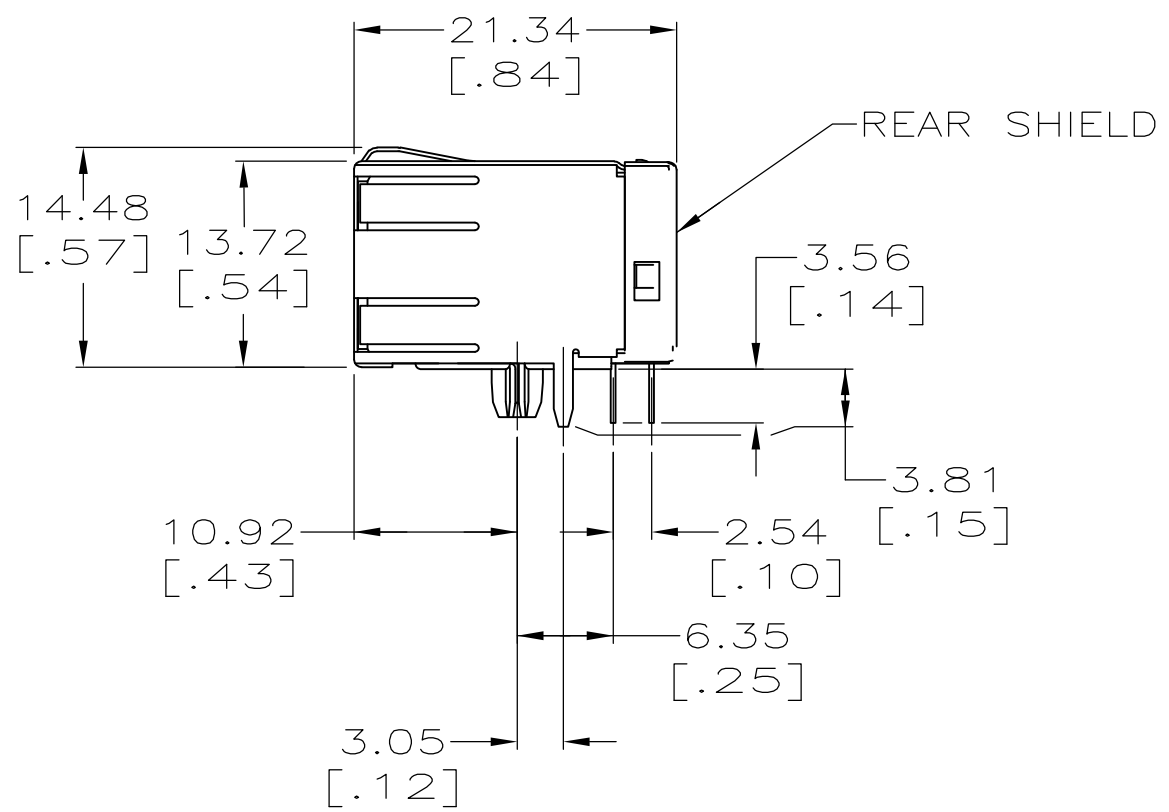
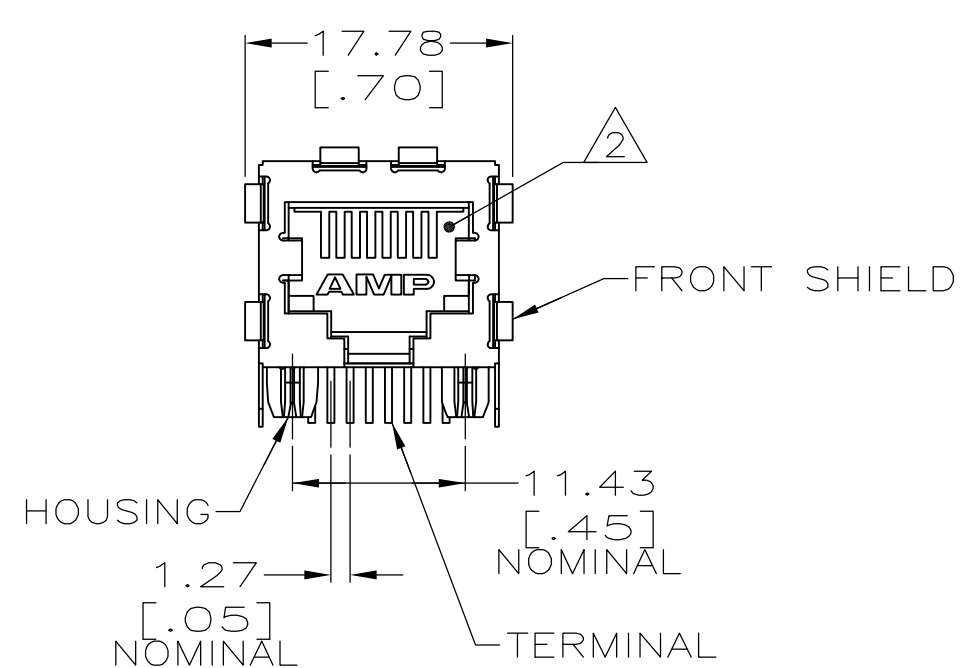
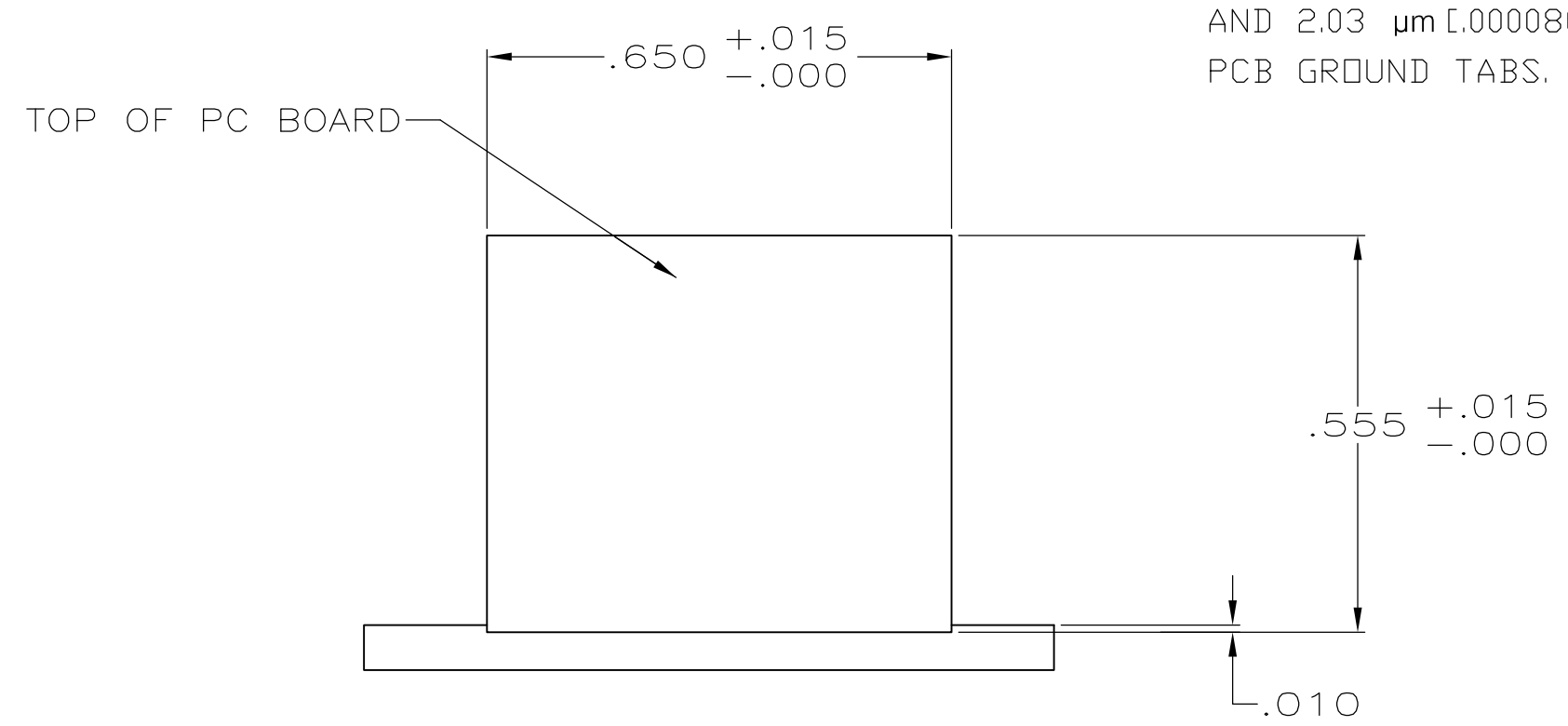
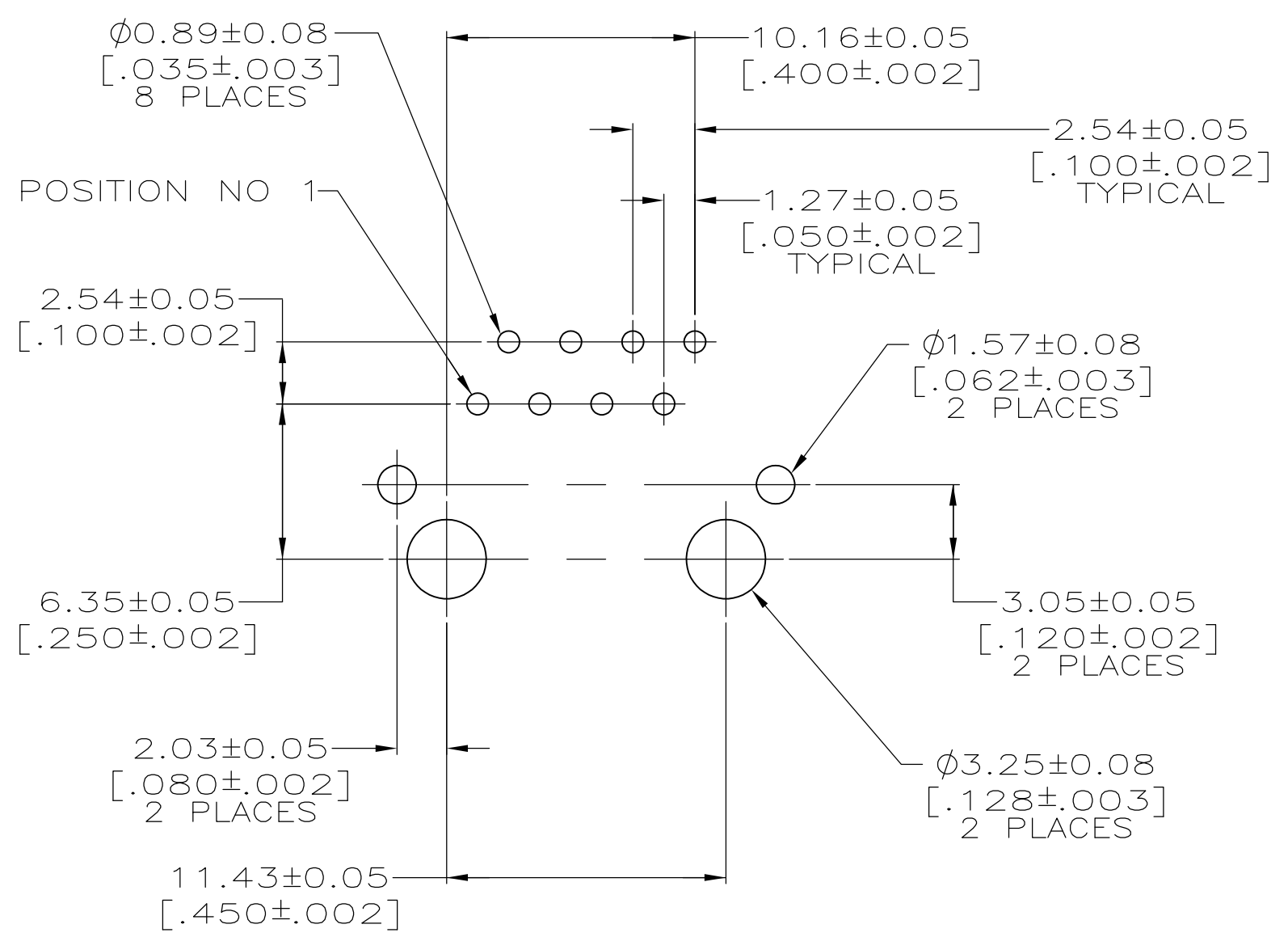




- 1 MATERIAL: HOUSING – NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0.
TERMINALS – 0.33 [.013] THICK PHOS BRONZE PLATED WITH 1.27 μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS – 0.25 [.010] THICK COPPER ALLOY PLATED WITH 2.03 μm [.000080] MINIMUM BRIGHT TIN OVER 1.27 μm [.000050] MINIMUM NICKEL
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- 4 MATERIAL: HOUSING – NYLON, BLACK, IR REFLOW COMPATIBLE, UL 94V-0.
TERMINALS – 0.33 [.013] THICK PHOS BRONZE PLATED WITH 1.27 μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS – 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 μm [.000050] MINIMUM NICKEL AND 2.03 μm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.



SUGGESTED PANEL CUTOUT
SCALE 4:1

SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE
SCALE 4:1

SUPERSEDED BY -2	4	5406298-2
	1	5406298-1
REMARK		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. SPRINKLE/LA.MAYER 20APR2005	 TE Connectivity				
		CHK J.WESTMAN 20APR2005					
DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD S.FLICKINGER 20APR2005	NAME	MODULAR JACK ASSEMBLY, SINGLE PORT, 8 POSITION, SHIELDED, REVERSE PANEL GROUND TABS, CATEGORY 4			
	0 PLC ± - 1 PLC ± - 2 PLC ± 0.25[.01] 3 PLC ± 0.13[.005] 4 PLC ± - ANGLES ± -	PRODUCT SPEC 108-1163 APPLICATION SPEC 114-2048					
	MATERIAL SEE NOTE 1&4	FINISH SEE NOTE 1&4	WEIGHT -				
		CUSTOMER DRAWING			SCALE 2:1	SHEET 1 of 1	REV D

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[5406298-2](#)